

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC2R5SN04C
Package Type :	PDFNWB5x6-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Si	7440-21-3	100.000%	0.528%
Lead Frame	Cu	7440-50-8	97.419%	29.664%
	Fe	7439-89-6	2.070%	
	Pb	7439-92-1	0.029%	
	P	7723-14-0	0.016%	
	Zn	7440-66-6	0.049%	
	Ag	7440-22-4	0.416%	
Die Attach	TIN - Sn	7440-31-5/231-141-8	11.535%	4.179%
	LEAD - Pb	7439-92-1/231-100-4	11.535%	
	SILVER - Ag	7440-22-4/231-131-3	3.651%	
	ANTIMONY - Sb	7440-36-0/231-146-5	13.023%	
	BISMUTH - Bi	7440-69-9/231-177-4	32.093%	
	INDIUM - Ln	7440-74-6/231-180-0	6.512%	
	COPPER - Cu	7440-50-8/231-159-6	0.256%	
	POILYGLYCOLETHER	9038-95-3	2.605%	
	CARBOXYLIC ACID	67762-36-1	1.302%	
	MODIFIED CASTER OIL	61788-85-0	3.907%	
	DODECYLPHENOL	27193-86-8	13.581%	
CLIP	P	7723-14-0	0.039%	7.048%
	Fe	7439-89-6	0.040%	
	Cu	7440-50-8	99.920%	
Wire	Au	7440-57-5	99.854%	0.666%
	others	/	0.146%	
Mold Compound	Epoxy resin A	Trade Secret	3.983%	57.335%
	Epoxy resin B	Trade Secret	3.186%	
	curing agent	Trade Secret	4.831%	
	catalyst	Trade Secret	4.990%	
	Carbon black	1333-86-4	0.159%	
	Silica(Amorphous) A	60676-86-0	61.017%	
	Silica(Amorphous) B	7631-86-9	21.834%	
Plating	Sn	7440-31-5	99.582%	0.581%
	others	/	0.418%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.